

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6059389

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the THE FIRST ASSIGNOR'S NAME previously recorded on Reel 047576 Frame 0516. Assignor(s) hereby confirms the ASSIGNMENT OF ASSIGNORS INTEREST.

CONVEYING PARTY DATA

Name	Execution Date
HSIEN-WEI CHEN	11/14/2018
MING-FA CHEN	11/14/2018
SUNG-FENG YEY	11/13/2018

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	NO.8, LI-HSIN RD. 6, HSINCHU SCIENCE PARK,
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	30078

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16199230

CORRESPONDENCE DATA**Fax Number:**

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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Correspondent Name: JCIPRNET

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Address Line 4: TAIPEI, TAIWAN 100404

ATTORNEY DOCKET NUMBER:	080682-US-PA
NAME OF SUBMITTER:	BELINDA LEE
SIGNATURE:	/Belinda Lee/
DATE SIGNED:	04/14/2020

Total Attachments: 5

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United States Patent and Trademark Office

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The coversheet of the assignment is displayed below:**PATENT ASSIGNMENT COVER SHEET**Electronic Version v1.1
Stylesheet Version v1.2

SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>HSIEN-WEI EN-CH <i>CHEN</i></td> <td>11/14/2018</td> </tr> <tr> <td>MING-FA CHEN</td> <td>11/14/2018</td> </tr> <tr> <td>SUNG-FENG YEH</td> <td>11/13/2018</td> </tr> </tbody> </table>		Name	Execution Date	HSIEN-WEI EN-CH <i>CHEN</i>	11/14/2018	MING-FA CHEN	11/14/2018	SUNG-FENG YEH	11/13/2018
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CORRESPONDENCE DATA									
Fax Number:	(949)391-4699								
Email:	USA@JICPGROUP.COM								

<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Correspondent Name:	JCIPRNET
Address Line 1:	P.O. BOX 600 TAIPEI GUTING
Address Line 4:	TAIPEI, TAIWAN 10099
ATTORNEY DOCKET NUMBER:	80682-US-PA
NAME OF SUBMITTER:	BELINDA LEE
Signature:	/Belinda Lee/
Date:	11/26/2018
Total Attachments: 3 source=80682_dcl-asm#page1.tif source=80682_dcl-asm#page2.tif source=80682_dcl-asm#page3.tif	
RECEIPT INFORMATION	
EPAS ID:	PAT5250017
Receipt Date:	11/26/2018

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P20180827US00
80682-US-PA

**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Declaration Submitted With Initial Filing

OR

Declaration Submitted After Initial Filing (surcharge 37 CFR 1.16(f) required)

(Title of the Invention)

PACKAGE STRUCTURE AND METHOD OF FABRICATING THE SAME

As a below named inventor (hereinafter designated as the undersigned), I hereby declare that:

This declaration is directed to:

The attached application,

OR

United States Application Number or PCT International application number

_____ Filed on _____

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the application.

The undersigned hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION

WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

WHEREAS, 1. Taiwan Semiconductor Manufacturing Co., Ltd.
of No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78,
R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring the undersigned's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

The undersigned further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

P20180827US00
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**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Hsien-Wei Chen Date: 2018.11.14

Legal Name of Sole or First Inventor: **Hsien-Wei Chen**

Residence: Hsinchu City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Ming-Fa Chen Date: 2018.11.14

Legal Name of Additional Joint Inventor, if any: **Ming-Fa Chen**

Residence: Taichung City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Sung-Feng Yeh Date: 2018.11.13

Legal Name of Additional Joint Inventor, if any: **Sung-Feng Yeh**

Residence: Taipei City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.